

Surface Mount Schottky Barrier Rectifier

FEATURES:

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

Circuit Diagram & Pin Configuration:



SOD-123FL



Marking

Type number	Marking code
DSK32	K32
DSK34	K34
DSK36	K36
DSK38	K38
DSK310	K310
DSK312	K312
DSK315	K315
DSK320	K320

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	DSK32	DSK34	DSK36	DSK38	DSK310	DSK312	DSK315	DSK320	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	3.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80								A
Max Instantaneous Forward Voltage at 3 A	V _F	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a = 100°C	I _R	0.5 10		0.3 5						mA
Typical Junction Capacitance ⁽¹⁾	C _j	250		160						pF
Typical Thermal Resistance ⁽²⁾	R _{θJA}	80								°C/W
Operating Junction Temperature Range	T _j	-55 ~ +150								°C
Storage Temperature Range	T _{stg}	-55 ~ +150								°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

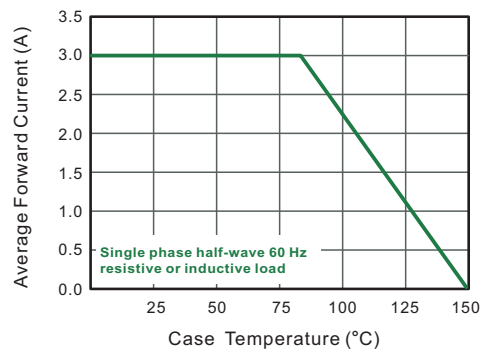


Fig.2 Typical Reverse Characteristics

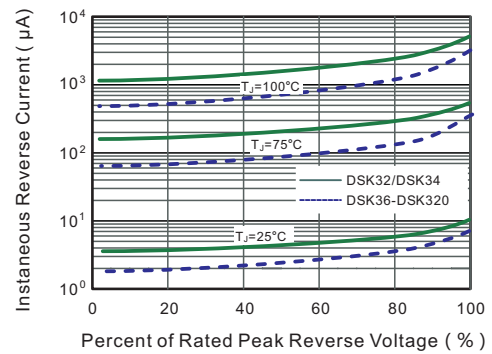


Fig.3 Typical Forward Characteristic

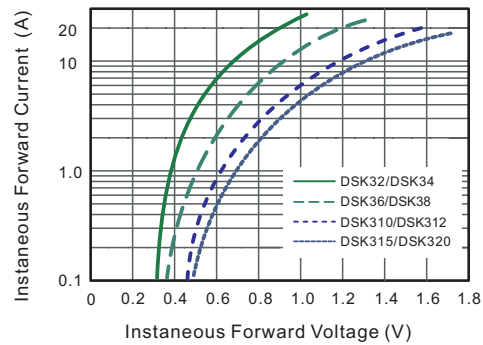


Fig.4 Typical Junction Capacitance

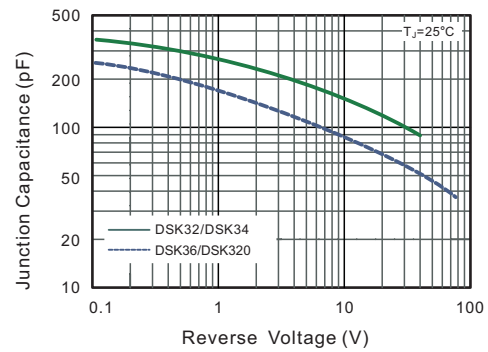


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

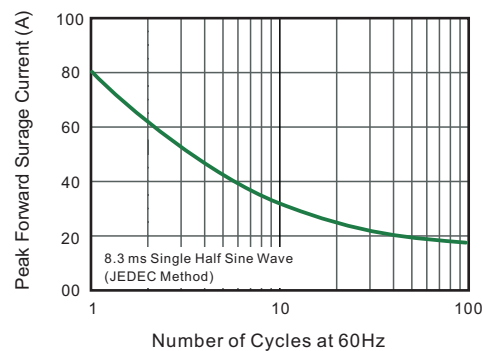
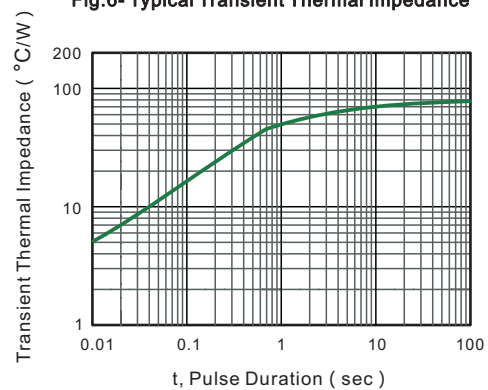


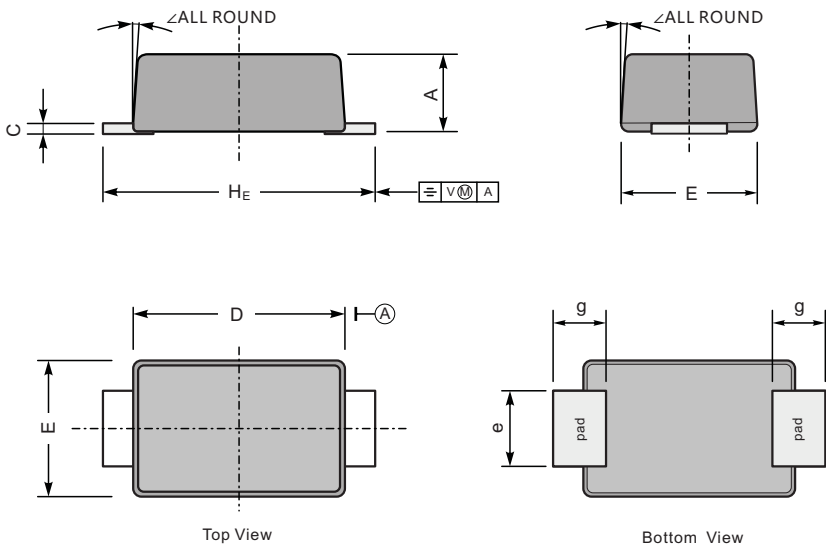
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

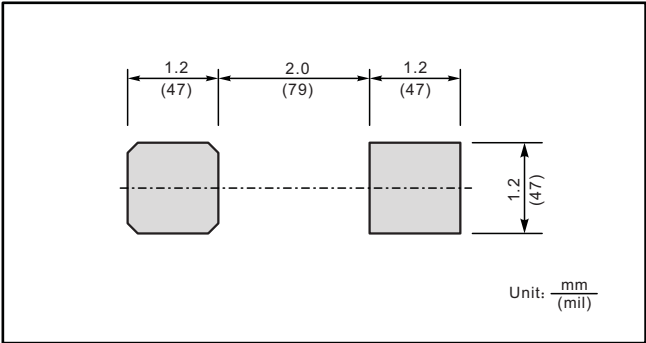
Plastic surface mounted package; 2 leads

SOD-123FL



UNIT		A	C	D	E	e	g	H _E	$\angle$
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size



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